

Special Issue

Innovations in 3D Printing 2.0

Message from the Guest Editor

Three-dimensional printing has been growing aggressively, and diverse thought leaders agree that additive manufacturing technology will cause a new industrial revolution, fundamentally changing the way products are made. In addition, the open-source self-replicating rapid prototyper project has created a tidal wave of innovation from hundreds of developers working together over the web. Enabled by 3-D printing, this allows for the efficient manufacture of geometrically and functionally complex products within a single process step, which provides enormous opportunities for more efficient product design, custom products, and rapid innovation in the product cycle. Three-dimensional printing also holds the potential for advances in global value chains, as well as manufacturing sustainability, including reduced energy consumption, increased materials efficiency, localized production, and increased opportunities for repair and life cycle upgrading. These opportunities will only be realized with continued invention and innovation. That is why I invite you to submit an article for *Inventions* for this Special Issue entitled *Innovations in 3-D Printing*.

Guest Editor

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Message from the Editorial Board

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